

ABSTRACT

METHOD FOR SEED LAYER REMOVAL FOR MAGNETIC HEADS

The electroplated components of a magnetic head of the present invention are fabricated
5 utilizing a seed layer that is susceptible to reactive ion etch removal techniques. A preferred
seed layer is comprised of tungsten or titanium. Following the electroplating of the components
utilizing a fluorine species reactive ion etch process the seed layer is removed, and significantly,
the fluorine RIE process creates a gaseous tungsten or titanium fluoride compound removal
product. The problem of seed layer redeposition along the sides of the electroplated components
10 is overcome because the gaseous fluoride compound is not redeposited. The present invention
also includes an enhanced two part seed layer, where the lower part is tungsten, titanium or
tantalum and the upper part is composed of the material that constitutes the component to be
electroplated.